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General Description

The SMA685xM series provides a highly-integrated solution by incorporating key components into one package – MOSFETs in a 3-phase full-bridge configuration, built-in protection functions such as UVLO (undervoltage lockout) and TD (thermal detection) circuits, pre-driver ICs with 7.5 V regulator output, and bootstrap diodes with limiting resistors.

The products are capable of detecting overcurrent through three shunt resistors. And their packages are fully-molded SIPs.

Applications

Include motor control for:

- · Air conditioner fan
- Air purifier fan
- · Washer-dryer fan

Features and Benefits

- Built-in bootstrap diodes with limiting resistors
- CMOS-compatible input (3.3 or 5 V)
- Built-in protection circuit for controlling power supply voltage drop (UVLO)
- Built-in overheat detection circuit (TD)
- Regulator output: 7.5 V, 35 mA
- Overcurrent detection enabled via three shunt resistors
- Small SIP (SMA, 24 pins)

Package

Package Name: SMA
 Pin Pitch: 1.27 mm
 External Size: 31 × 10.2 × 4 mm

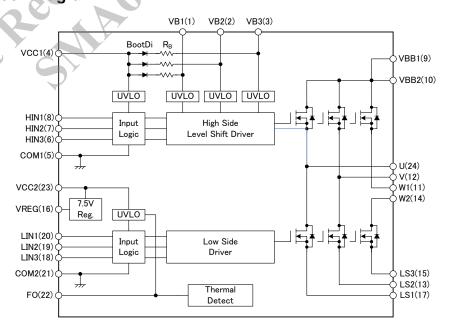


Not to scale

Product Specifications

Part Number	$\begin{array}{c} MOSFET \\ Breakdown \\ Voltage, V_{DDS} \\ (V) \end{array}$	Output Current (Continuous), I ₀ (A)	MOSFET On-Resistance, $R_{DS(ON)}$ (Ω Max.)
SMA6852MZ	500	1.5	4.0
SMA6853MX	500	2.5	2.4
SMA6854MZ	600	1.5	3.5

Functional Block Diagram



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1. Scope

The specifications described in this document shall apply to the SMA685xM series, high-voltage 3-phase motor driver ICs.

2. Absolute Maximum Ratings, valid at $T_A = 25$ °C

Characteristics	Symbol		Remarks		
		SMA6852MZ	$V_{CC} = 15 \text{ V}, I_D = 100 \mu\text{A}, \ V_{IN} = 0 \text{ V}$	500	V
MOSFET Breakdown Voltage	V_{DSS}	SMA6853MX	$V_{CC} = 15 \text{ V}, I_D = 100 \mu\text{A}, \ V_{IN} = 0 \text{ V}$	500	V
		SMA6854MZ	$V_{CC} = 15 \text{ V}, I_D = 100 \mu\text{A}, \ V_{IN} = 0 \text{ V}$	600	V
Logic Supply Voltage	V_{CC}	Between VCC a	and COM	20	V
Bootstrap Voltage	V_{BS}	Between VB an	d phase U, V, or W	20	V
		SMA6852MZ		1.5	A
Output Current (Continuous)	I_{O}	SMA6853MX	2.5	A	
		SMA6854MZ	:07	1.5	Α
	I _{OP}	SMA6852MZ	$P_W \le 100 \ \mu s$	2.25	Α
Output Current (Pulsed)		SMA6853MX	$P_W \le 100 \ \mu s$	3.75	Α
		SMA6854MZ	$P_W \le 100 \ \mu s$	2.25	Α
Output Current for Regulator	I_{REG}	70,		35	mA
Input Voltage	V _{IN}	HIN and LIN p	ins	-0.5 to 7	V
Allowable Power Dissipation	P_{D}	$T_C = 25^{\circ}C$		28	W
Thermal Resistance (Junction-to-Case)	$R_{j-\varepsilon}$	All elements op	perating	4.46	°C/W
Thermal Resistance (Junction-to-Ambient)	R_{j-a}	All elements op	perating	31.25	°C/W
Case Operating Temperature	$T_{C(OP)}$			-20 to 100	°C
Junction Temperature	T_{j}			150	°C
Storage Temperature	$T_{ m stg}$			-40 to 150	°C

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3. Electrical Characteristics

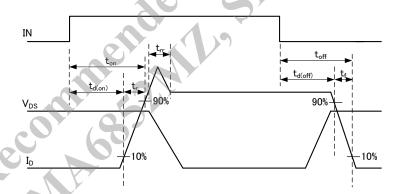
3-1. Electrical Characteristics, valid at T_a = 25°C, V_{CC} = 15 V

Chamatanistias	Crymbal	Remarks -		Ratings			Unit
Characteristics	Symbol			Min.	Typ.	Max.	OIII
Logic Supply Current	I_{CC}	$I_{REG} = 0 A$			2.5	4	mA
	V_{IH}	Output ON			2.0	2.5	V
Input Voltage	$V_{\rm IL}$	Output OFF		1.0	1.5	•	V
	V _{HYS}	Hysteresis			0.5	9	V
Leavet Comment	I_{IH}	$V_{IN} = 5 \text{ V}$		_	50	100	μΑ
Input Current	$I_{\rm IL}$	$V_{IN} = 0 V$		— %		2	μΑ
	V_{UVHL}	Between VB and	d U, V, or W	9.0	10.0	11.0	V
Undervoltage Lockout (Bootstrap)	V _{UVHH}	Between VB and	d U, V, or W	9.5	10.5	11.5	V
(Bootstap)	V _{UVhys}	Between VB and	d U, V, or W; hysteresis	<u> </u>	0.5	<i>></i> —	V
	V_{UVLL}	Between VCC	and COM	10.0	11.0	12.0	V
Undervoltage Lockout (Logic Supply)	V _{UVLH}	Between VCC	and COM	10.5	11.5	12.5	V
(Logic Supply)	V _{UVhys}	Between VCC	and COM; hysteresis		0.5		V
EO Tamain al Outant Valta a	V _{FOL}			0		1.0	V
FO Terminal Output Voltage	V _{FOH}			4.0		5.5	V
Overheat Detection	T_{DH}	$I_{REG} = 0$ mA, no	135	150	165	°C	
Threshold Temperature	T_{DL}	$I_{REG} = 0$ mA, no	105	120	135	°C	
(Activation/Deactivation)	T _{DHYS}	$I_{REG} = 0$ mA, no	heatsink, hysteresis		30		°C
Output Voltage for Regulator	V_{REG}	$I_{REG} = 0$ to 35 m	A	6.75	7.5	8.25	V
D		SMA6852MZ	$V_R = 500 \text{ V}$	_		10	μΑ
Bootstrap Diode Leakage Current	I_{LBD}	SMA6853MX	$V_R = 500 \text{ V}$			10	μΑ
Current		SMA6854MZ	$V_{R} = 600 \text{ V}$			10	μΑ
Bootstrap Diode Forward Voltage	V_{FB}	$I_{FB} = 0.15 \text{ A}$			1.1	1.3	V
		SMA6852MZ		17.6	22.0	26.4	Ω
Bootstrap Diode Series Resistor	R _B	SMA6853MX		17.6	22.0	26.4	Ω
Resistor		SMA6854MZ	48	60	72	Ω	
	C V	SMA6852MZ	$V_{DS} = 500 \text{ V}, V_{IN} = 0 \text{ V}$	_	_	100	μΑ
MOSFET Breakdown Voltage	$I_{ m DSS}$	SMA6853MX	$V_{DS} = 500 \text{ V}, V_{IN} = 0 \text{ V}$	_	_	100	μΑ
40 6	Y	SMA6854MZ	$V_{DS} = 600 \text{ V}, V_{IN} = 0 \text{ V}$	_	_	100	μΑ
		SMA6852MZ	$I_D = 0.75 \text{ A}, V_{IN} = 5 \text{ V}$		3.6	4.0	Ω
MOSFET On-Resistance	R _{DS(ON)}	SMA6853MX	$I_D = 1.25 \text{ A}, V_{IN} = 5 \text{ V}$		2.0	2.4	Ω
		SMA6854MZ	$I_D = 0.75 \text{ A}, V_{IN} = 5 \text{ V}$	_	3.0	3.5	Ω
		SMA6852MZ	$I_{SD} = 0.75 \text{ A}, V_{IN} = 0 \text{ V}$	_	1.1	1.5	V
MOSFET Diode Forward Voltage	V_{SD}	SMA6853MX	$I_{SD} = 1.25 \text{ A}, V_{IN} = 0 \text{ V}$	_	1.1	1.5	V
voltage		SMA6854MZ	$I_{SD} = 0.75 \text{ A}, V_{IN} = 0 \text{ V}$		1.1	1.5	V

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3-1. Electrical Characteristics, valid at $T_a = 25$ °C (continued)

<u> </u>	ti icai Ci	iai acter istic	s, valid at I _a = 25 C (COIICII	iucuj					
	Symbol Remarks			Ratings						
Characteristics			Remarks	emarks H-Side			L-Side			Unit
				Min.	Тур.	Max.	Min.	Тур.	Max.	
	$t_{d(on)}$		$\begin{aligned} &V_{DC}=300 \text{ V,} \\ &V_{CC}=15 \text{ V,} \\ &I_D=1.5 \text{ A,} \\ &V_{IN}=0 {\longrightarrow} 5 \text{ V or } 5 {\longrightarrow} 0 \text{ V,} \\ &T_j=25 {^{\circ}C}, \\ &inductive load \end{aligned}$		530	_	_	530	_	ns
	t _r				95	_		95		ns
	t _{rr}	SMA6852MZ			130	_		120	_	ns
	$t_{d(off)}$				385	_	-,4	445		ns
	t_{f}			_	40	_	E)	30		ns
	$t_{d(on)}$	SMA6853MX	$\begin{split} V_{DC} &= 300 \text{ V}, \\ V_{CC} &= 15 \text{ V}, \\ I_D &= 2.5 \text{ A}, \\ V_{IN} &= 0 {\rightarrow} 5 \text{ V or } 5 {\rightarrow} 0 \text{ V}, \\ T_j &= 25 {^{\circ}C}, \\ \text{inductive load} \end{split}$	_	650	- (77	700		ns
	$t_{\rm r}$				100		\ \ \ !	100	_	ns
Switching Time	t_{rr}				150	—	_	150	_	ns
	$t_{d(off)}$				520	Y	+	580	—	ns
	$t_{\rm f}$				50	_		40		ns
	$t_{d(on)}$		$V_{DC} = 300 \text{ V},$ $V_{CC} = 15 \text{ V},$ $I_D = 1.5 \text{ A},$ $V_{IN} = 0 \rightarrow 5 \text{ V or } 5 \rightarrow 0 \text{ V},$	3	530	5		530		ns
	$t_{\rm r}$				55		—	60		ns
	t _{rr}	SMA6854MZ			125	<u> </u>		125		ns
	$t_{d(off)}$		$T_j = 25^{\circ}C$,	_ \	510		_	540		ns
	t_{f}		inductive load	A	50			55		ns



Switching Characteristics Definitions

3-2. Recommended Operating Conditions

5-2. Recommended Operating Conditions									
Characteristics	Cumbal	Remarks		Ratings			Unit		
Characteristics	Symbol			Min.	Typ.	Max.	Oilit		
		SMA6852MZ	Between VBB and LS	_	300	400	V		
Main Supply Voltage	V_{DC}	SMA6853MX	Between VBB and LS	_	300	400	V		
		SMA6854MZ	Between VBB and LS	_	300	450	V		
Logic Supply Voltage	V _{CC}	Between VCC and COM		13.5		16.5	V		
Minimum Input Pulse Width	t _{INmin(on)}			0.5			μs		
Willimian input ruise widin	$t_{INmin(off)}$			0.5			μs		
Dead Time	t _{dead}			1.5			μs		

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3-3. Truth Table

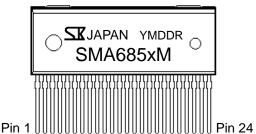
Mode	HIN	LIN	High-Side MOSFET	Low-Side MOSFET
	L	L	OFF	OFF
No	Н	L	ON	OFF
Normal	L	Н	OFF	ON
	Н	Н	ON	ON
	L	L	OFF	OFF
Thomas Detection (TD)	Н	L	ON	OFF
Thermal Detection (TD)	L	Н	OFF	ON
	Н	Н	ON	ON
	L	L	OFF	OFF
UVLO (VCC)	Н	L	OFF	OFF
UVLO (VCC)	L	Н	OFF	OFF
	Н	Н	OFF	OFF
	L	L	OFF	OFF
UVLO (VB)	Н	L	OFF	OFF
UVLU(VB)	L	Н	OFF	ON
	Н	Н	OFF	ON

NOTES:

- An arm short-circuit may occur when inputs on the HIN and LIN pins for the same phase are all logic high. Therefore, extra attention should be paid to prevent a condition in which the pins for the same phase are fully ON at once.
- A MOSFET in a V_{CC} UVLO state gets re-activated when an input signal is detected at a certain logic level (level triggering), while a MOSFET in a V_B UVLO state resumes its operation at a point where an input signal transits from one state to another (edge triggering).

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4. Pin-Out Diagram

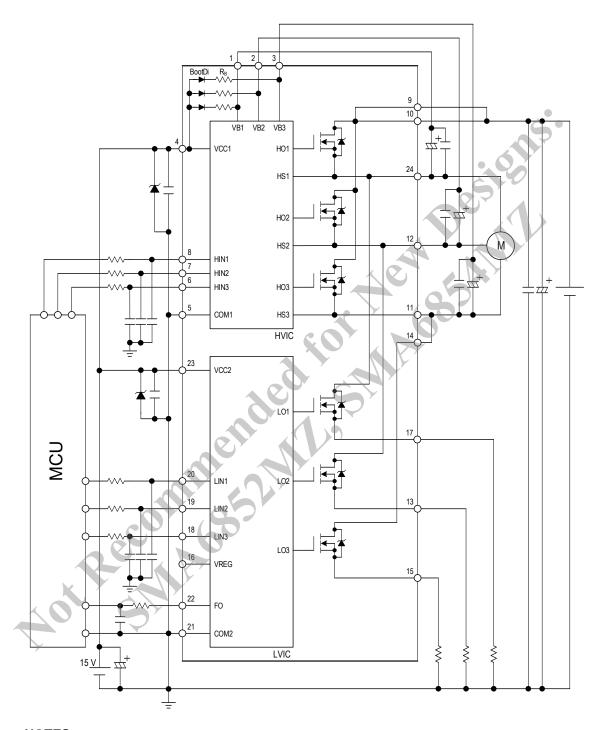


Terminal List Table

Pin Number	Pin Name	Functions	I/O
1	VB1	High-side bootstrap (phase U)	_
2	VB2	High-side bootstrap (phase V)	_
3	VB3	High-side bootstrap (phase W)	_
4	VCC1	High-side logic supply voltage	—
5	COM1	High-side logic GND	
6	HIN3	High-side input (phase W)	Input
7	HIN2	High-side input (phase V)	Input
8	HIN1	High-side input (phase U)	Input
9	VBB1	Main supply voltage 1 (connected to VBB2 externally)	_
10	VBB2	Main supply voltage 2 (connected to VBB1 externally)	_
11	W1	Phase W output (connected to W2 externally)	_
12	V	Phase V output	
13	LS2	Low-side source (phase V)	_
14	W2	Phase W output (connected to W1 externally)	
15	LS3	Low-side source (phase W)	
16	VREG	Internal regulator output	Output
17	LS1	Low-side source (phase U)	
18	LIN3	Low-side input (phase W)	Input
19	LIN2	Low-side input (phase V)	Input
20	LIN1	Low-side input (phase U)	Input
21	COM2	Low-side logic GND	_
22	FO	Error output	Output
23	VCC2	Low-side logic supply voltage	_
24	U	Phase U output	

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5. Application Example

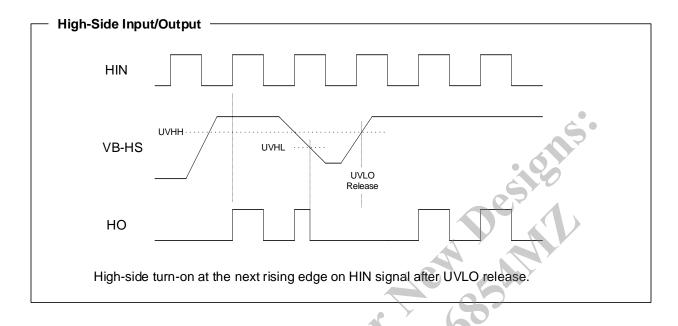


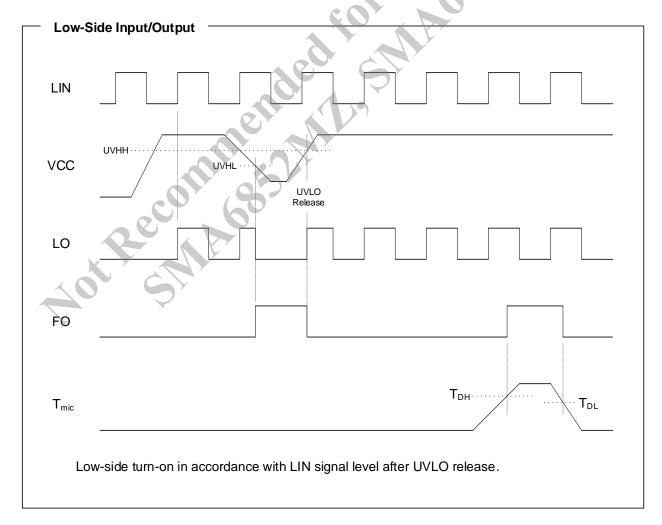
NOTES:

- All of the input pins are connected to GND with internal pull-down resistors rated at 100 kΩ. However, an external pull-down resistor may be required to secure stable condition of the inputs if high impedance conditions are applied to them.
- The external electrolytic capacitors should be placed as close to the IC as possible, in order to avoid malfunctions from external noise interference. Put a ceramic capacitor in parallel with the electrolytic capacitor if further reduction of noise susceptibility is necessary.

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6. Timing Diagrams for Protection Operations

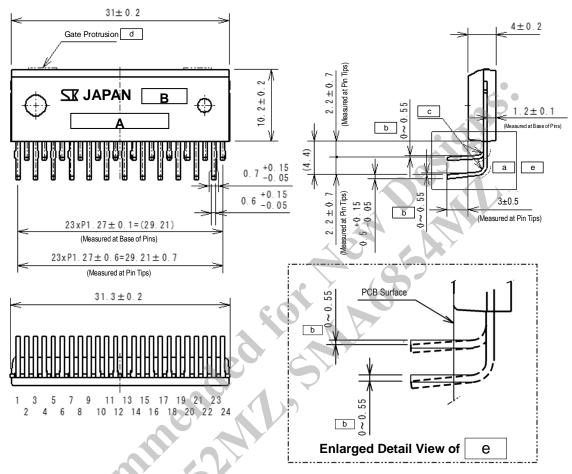




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7. Package Outline Drawing

7-1. Leadform 2451 (Dimensions in Millimeters)



NOTES:

- a depicts the intentionally-curved part of a pin whose plated surface may easily be cracked and/or peeled off. Note that this kind of damaged surface does NOT indicate negative effects on terminal flexural toughness or any other reliability characteristics.
- b represents terminal curvature exaggerated for illustration purposes, not actual states of being bent or curved.
- c shows pins with a minimum inside radius (R) of 0.65 mm.
- describes the area(s) where either one or two gate protrusions up to 0.3 mm high will appear on the package surface, drawn with dashed double-dotted lines. (The number of gate protrusions varies depending on the package mold type used.)
- Branding Codes

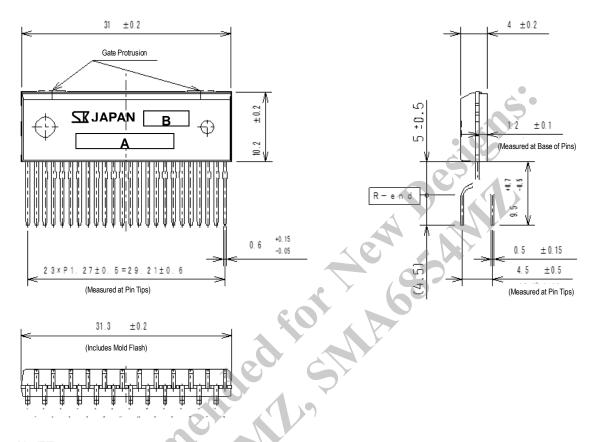
A. Part number: *SMA685xMX/MZ*

B. Lot number: *YMDDR*

- *Y* is the last digit of the year of manufacture
- M is the month of the year manufactured (1 to 9, O, N, or D)
- DD is the day of the month manufactured (01 to 31)
- R is the Sanken control number

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7-2. Leadform 2452 (Dimensions in Millimeters)



NOTE: Either one or two gate protrusions up to 0.3 mm high will appear on the package surface, as drawn with dashed double-dotted lines in the illustration above. (The number of gate protrusions varies depending on the package mold type used.)

■ Branding Codes

A. Part number: *SMA685xMX/MZ*

B. Lot number: *YMDDR*

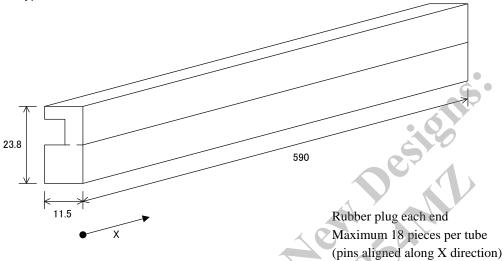
- Y is the last digit of the year of manufacture
- *M* is the month of the year manufactured (1 to 9, O, N, or D)
- DD is the day of the month manufactured (01 to 31)
- R is the Sanken control number

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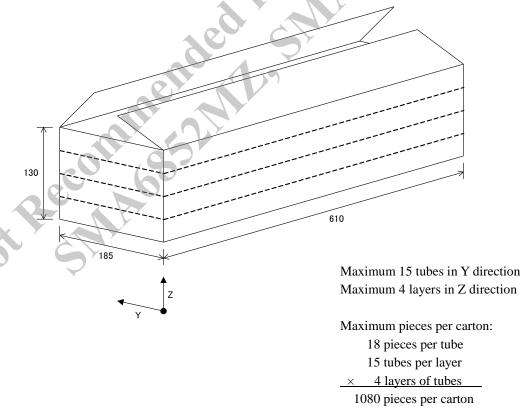
8. Packing Specifications

8-1. Leadform 2451 (Dimensions in Millimeters)

■ Tube Type: SCM-C



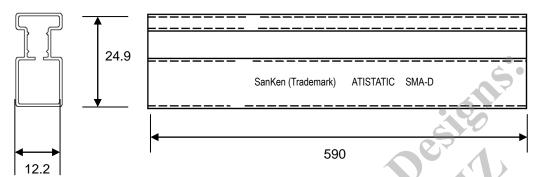
■ Corrugated Shipping Carton



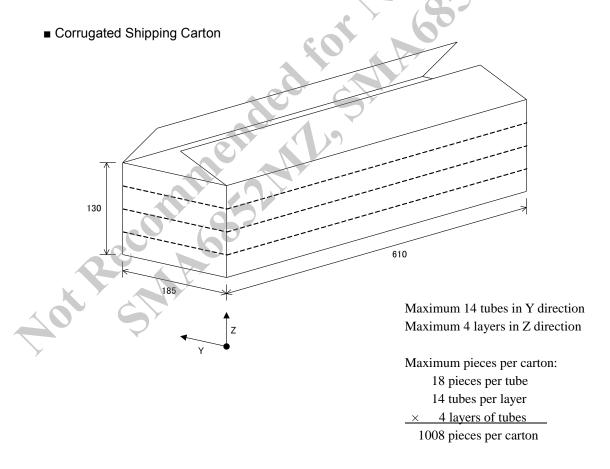
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8-2. Leadform 2452 (Dimensions in Millimeters)

■ Tube Type: SMA-D



Rubber plug each end Maximum 18 pieces per tube (pins aligned along X direction)



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